

#	Layer	Thickness	Description	Dk	Df	Note
	Top Solder	0.015mm	Soldermask IPC-SM840	3,5	0,028	used on rigid parts
1	Top Side	0.030mm	Starting foil 1/4oz. after plating and processing	3,5	0,011	FR-4.1 filled, halogen free
		0.065mm	Prepreg IPC-4101/127/128			
2	Inner Layer 1	0.035mm	ED Base Copper	4,5	0,011	FR-4.1 filled, halogen free
		0.300mm	Core IPC-4101/127/128			
3	Inner Layer 2	0.035mm	ED Base Copper	3,7	0,011	FR-4.1 filled, halogen free
		0.174mm	Prepreg IPC-4101/127/128			
4	Inner Layer 3	0.035mm	ED Base Copper	4,5	0,011	FR-4.1 filled, halogen free
		0.300mm	Core IPC-4101/127/128			
5	Inner Layer 4	0.035mm	ED Base Copper	3,7	0,011	FR-4.1 filled, halogen free
		0.174mm	Prepreg IPC-4101/127/128			
6	Inner Layer 5	0.035mm	ED Base Copper	4,5	0,011	FR-4.1 filled, halogen free
		0.300mm	Core IPC-4101/127/128			
7	Inner Layer 6	0.035mm	ED Base Copper	3,5	0,011	FR-4.1 filled, halogen free
		0.065mm	Prepreg IPC-4101/127/128			
8	Bottom Side	0.030mm	Starting foil 1/4oz. after plating and processing	3,5	0,028	used on rigid parts
	Bottom Solder	0.015mm	Soldermask IPC-SM840	3,5	0,028	used on rigid parts
Total thickness: 1.678mm						

notes:

Final copper thickness according to IPC-6012

Please regard to our sectional design rules:
▶ www.we-online.com

HDI8_1-6-1_1,68_35_V2.12

PCB Thickness Tolerance: ± 10%

customer	created
pcb name	approved
engineer	format
date	A4, landscape

Template Revision: 02/2021 by Andreas Schilpp / Michael Kress / Werner Öchslen

